

V_{RRM}	=	4500 V
I_{FAVM}	=	1400 A
I_{FSM}	=	25 kA
V_{F0}	=	1.2 V
r_F	=	0.32 mΩ
V_{DClink}	=	2200 V

Fast Recovery Diode

5SDF 14H4505

Doc. No. 5SYA1110-02 Sep. 01

- Patented free-floating silicon technology
- Low on-state and switching losses
- Optimized for use as freewheeling diode in GTO converters with low DC link voltages
- Standard press-pack housing, hermetically plasma-welded
- Cosmic radiation withstand rating

Blocking

V_{RRM}	Repetitive peak reverse voltage	4500 V	Half sine wave, $t_P = 10$ ms, $f = 50$ Hz
I_{RRM}	Repetitive peak reverse current	≤ 50 mA	$V_R = V_{RRM}, T_j = 125^\circ\text{C}$
V_{DClink}	Permanent DC voltage for 100 FIT failure rate	2200 V	100% Duty
V_{DClink}	Permanent DC voltage for 100 FIT failure rate	V	5% Duty Ambient cosmic radiation at sea level in open air.

Mechanical data (see Fig. 12)

F_m	Mounting force	min.	36 kN	
		max.	44 kN	
a	Acceleration: Device unclamped Device clamped		50 m/s ² 200 m/s ²	
m	Weight		0.83 kg	
D_s	Surface creepage distance	\geq	30 mm	
D_a	Air strike distance	\geq	20 mm	

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On-state (see Fig. 2, 3)

I_{FAVM}	Max. average on-state current	1400 A	Half sine wave, $T_c = 85^\circ\text{C}$		
I_{FRMS}	Max. RMS on-state current	2200 A			
I_{FSM}	Max. peak non-repetitive surge current	25 kA	$tp = 10 \text{ ms}$	Before surge: $T_c = T_j = 125^\circ\text{C}$	
		60 kA	$tp = 1 \text{ ms}$		
$\int i^2 dt$	Max. surge current integral	$3.13 \cdot 10^6 \text{ A}^2\text{s}$	$tp = 10 \text{ ms}$	After surge: $V_R \approx 0 \text{ V}$	
		$1.8 \cdot 10^6 \text{ A}^2\text{s}$	$tp = 1 \text{ ms}$		
V_F	Forward voltage drop	$\leq 2 \text{ V}$	$I_F = 2500 \text{ A}$	$T_j = 125^\circ\text{C}$	
V_{FO}	Threshold voltage	1.2 V	Approximation for		
r_F	Slope resistance	0.32 mΩ	$I_F = 400 \dots 4000 \text{ A}$		

Turn-on (see Fig. 4, 5)

V_{fr}	Peak forward recovery voltage	$\leq 30 \text{ V}$	$di/dt = 500 \text{ A}/\mu\text{s}, T_j = 125^\circ\text{C}$
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Turn-off (see Fig. 6 to 11)

I_{rr}	Reverse recovery current	$\leq 1000 \text{ A}$	$di/dt = 300 \text{ A}/\mu\text{s}, I_F = 1000 \text{ A},$
Q_{rr}	Reverse recovery charge	$\leq 3700 \mu\text{C}$	$T_j = 125^\circ\text{C}, V_{RM} = 4500 \text{ V},$
E_{rr}	Turn-off energy	$\leq 1.6 \text{ J}$	$C_S = 3\mu\text{F}$ (GTO snubber circuit)

Thermal (see Fig. 01)

T_j	Operating junction temperature range	-40...125°C		
T_{stg}	Storage temperature range	-40...125°C		
R_{thJC}	Thermal resistance junction to case	$\leq 24 \text{ K/kW}$	Anode side cooled	$F_m = 36 \dots 44 \text{ kN}$
		$\leq 24 \text{ K/kW}$	Cathode side cooled	
		$\leq 12 \text{ K/kW}$	Double side cooled	
R_{thCH}	Thermal resistance case to heatsink	$\leq 6 \text{ K/kW}$	Single side cooled	
		$\leq 3 \text{ K/kW}$	Double side cooled	

Analytical function for transient thermal impedance.

$$Z_{thJC}(t) = \sum_{i=1}^n R_i (1 - e^{-t/\tau_i})$$

i	1	2	3	4
$R_i(\text{K/kW})$	7.44	2.00	1.84	0.71
$\tau_i(\text{s})$	0.47	0.091	0.011	0.0047
$F_m = 36 \dots 44 \text{ kN}$ Double side cooled				

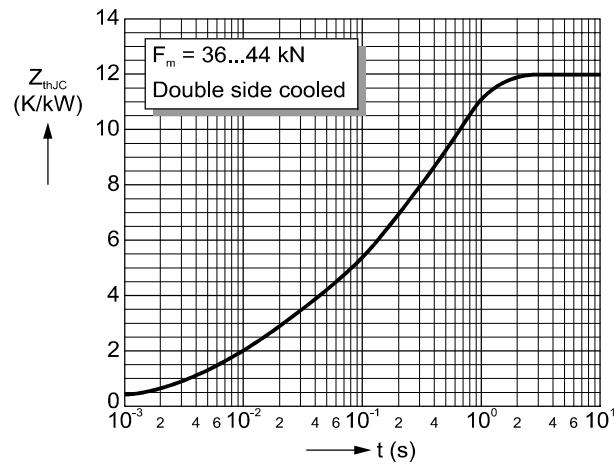


Fig. 1 Outline drawing. All dimensions are in millimeters and represent nominal values unless stated otherwise.

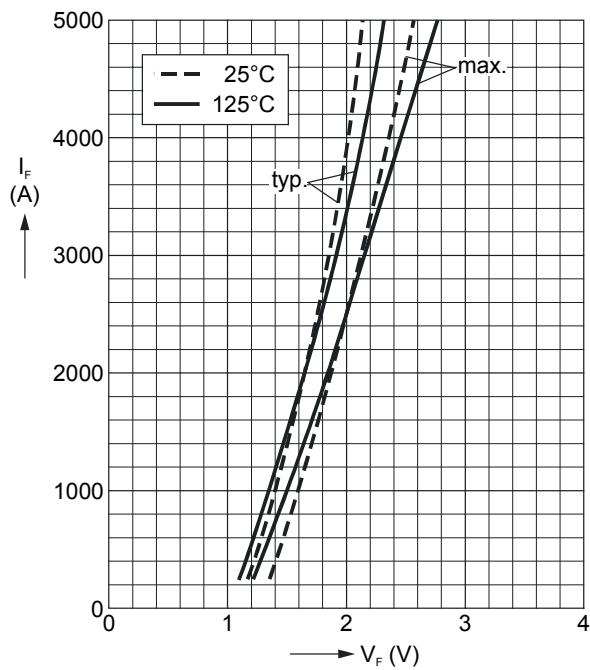


Fig. 2 Forward current vs. forward voltage (typ. and max. values) and linear approximation of max. curve at 125°C .

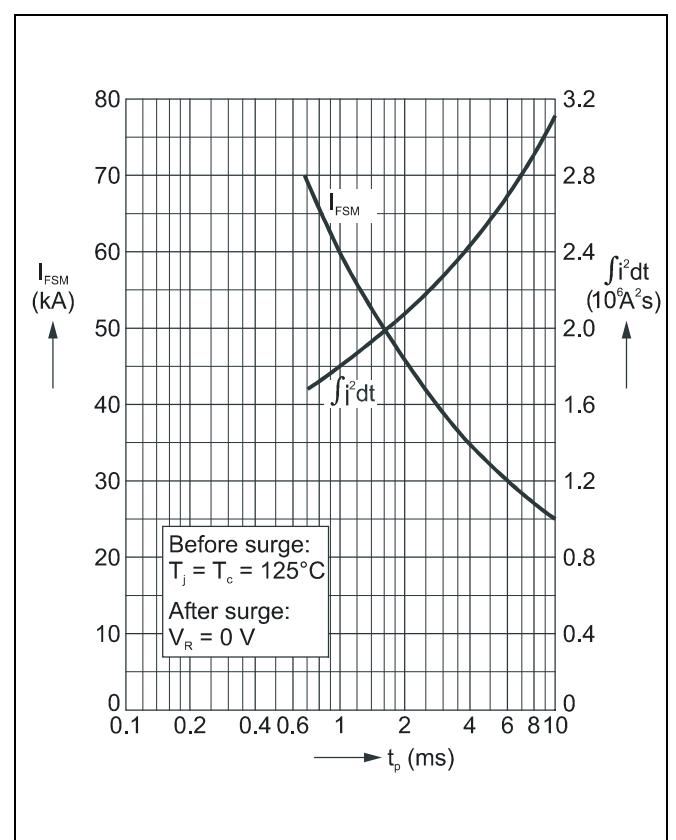


Fig. 3 Surge current and fusing integral vs. pulse width (max. values) for non-repetitive, half-sinusoidal surge current pulses.

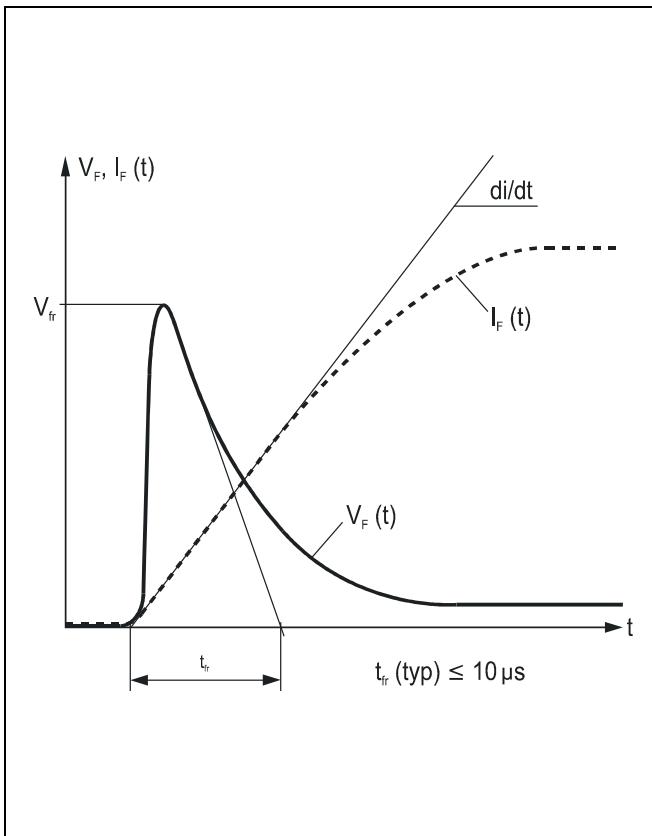


Fig. 4 Typical forward voltage waveform when the diode is turned on with a high di/dt .

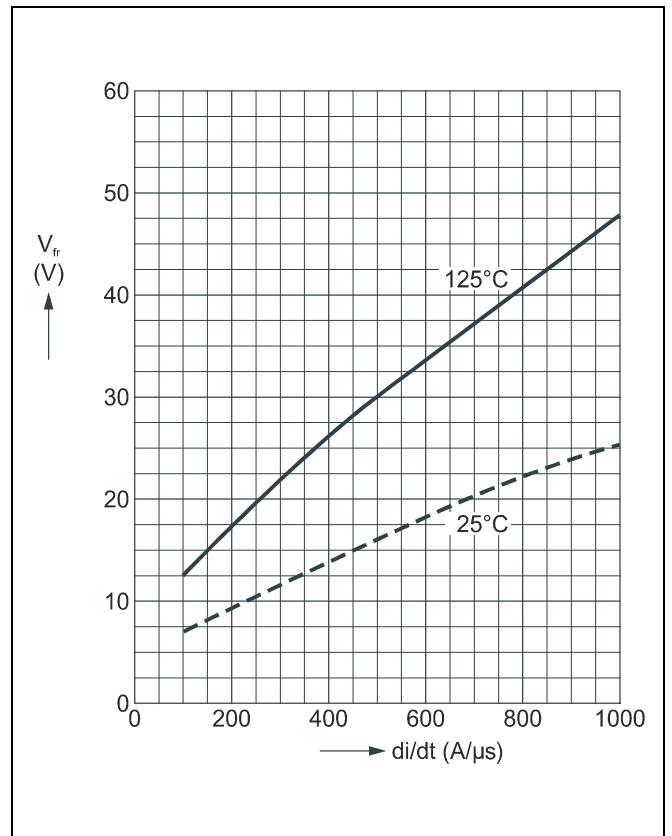


Fig. 5 Forward recovery voltage vs. turn-on di/dt (max. values).

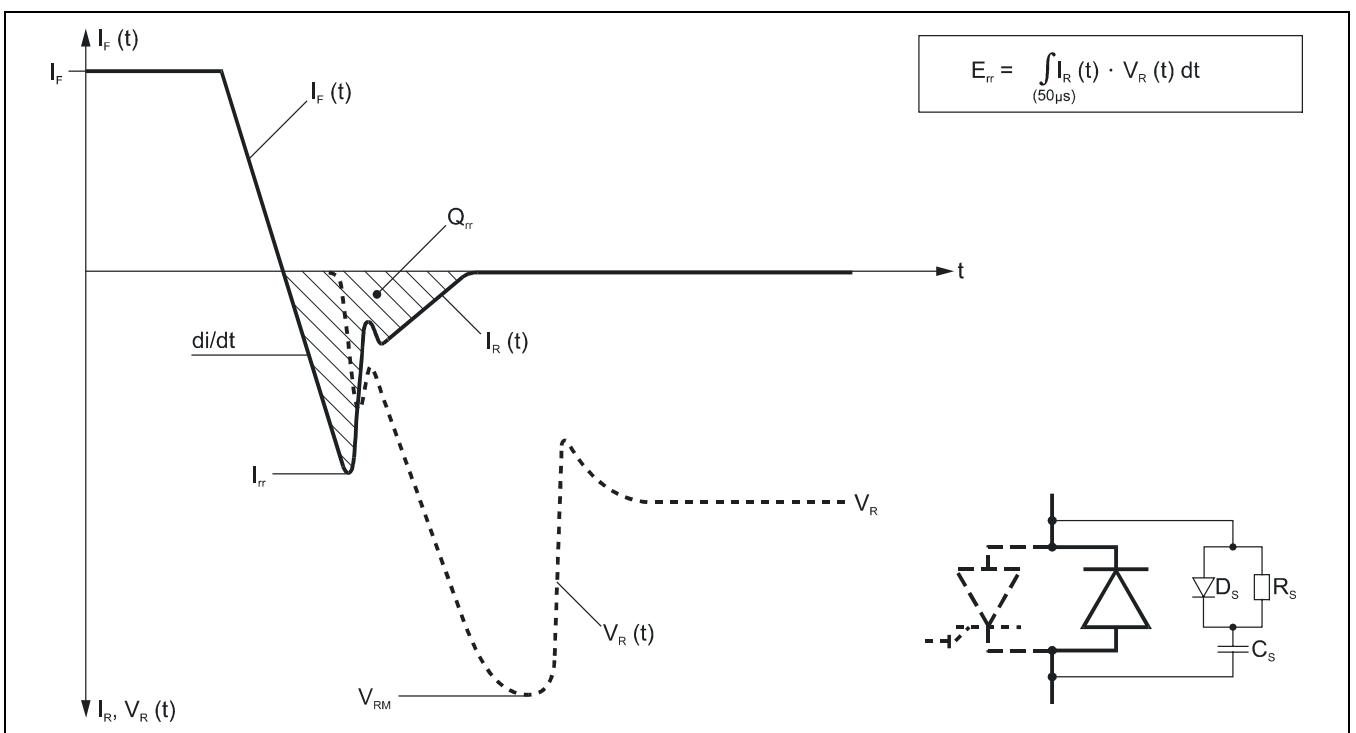


Fig. 6 Typical current and voltage waveforms at turn-off when the diode is connected to an RCD snubber, as often used in GTO circuits.

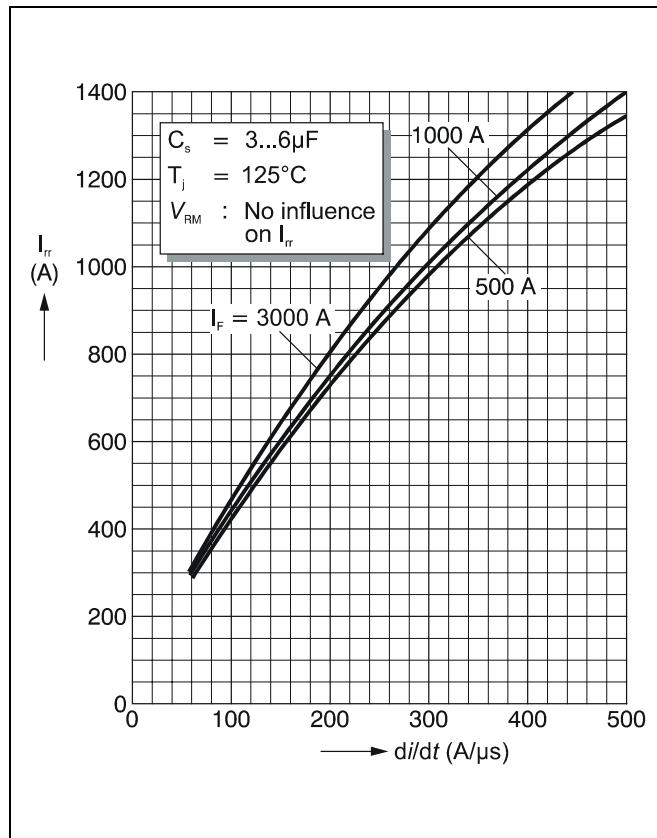


Fig. 7 Reverse recovery current vs. turn off di/dt (max. values).

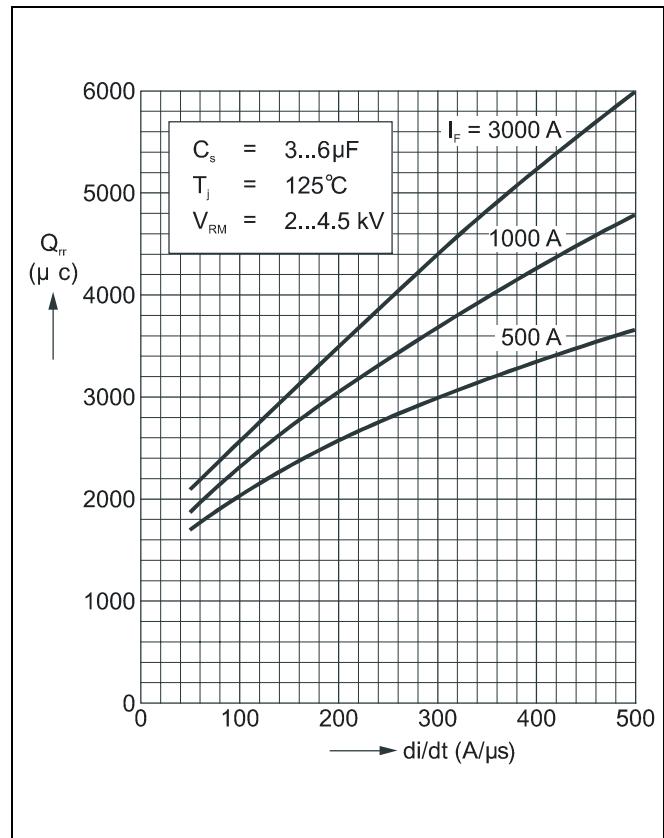


Fig. 8 Reverse recovery charge vs. turn off di/dt (max. values).

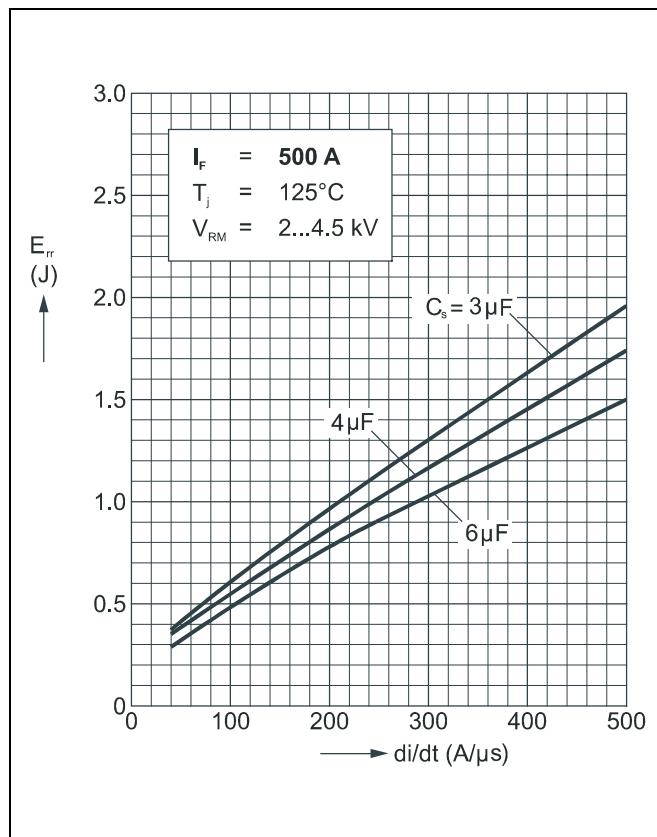


Fig. 9 Turn-off energy vs. turn-off di/dt for $I_F = 500$ A (max. values).

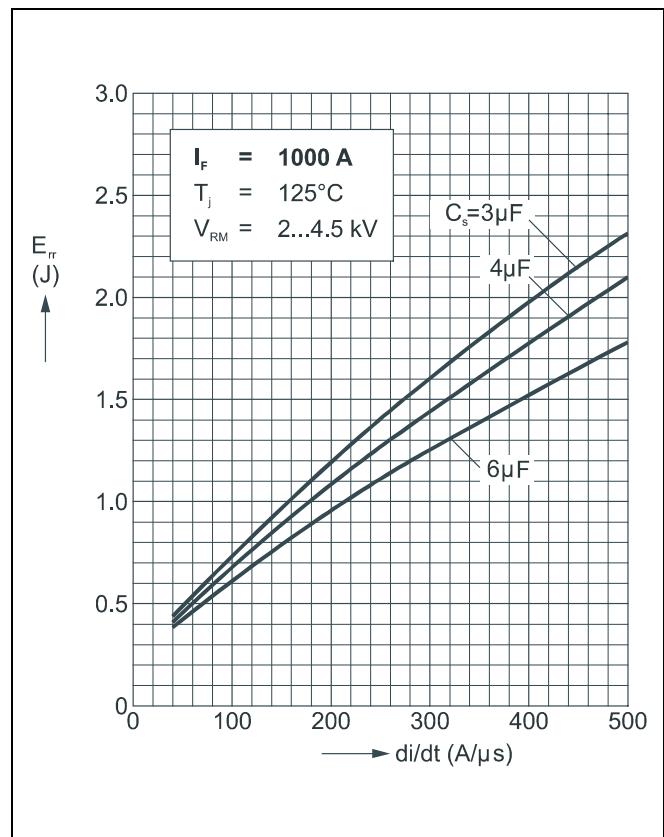


Fig. 10 Turn-off energy vs. turn-off di/dt for $I_F = 1000$ A (max. values).

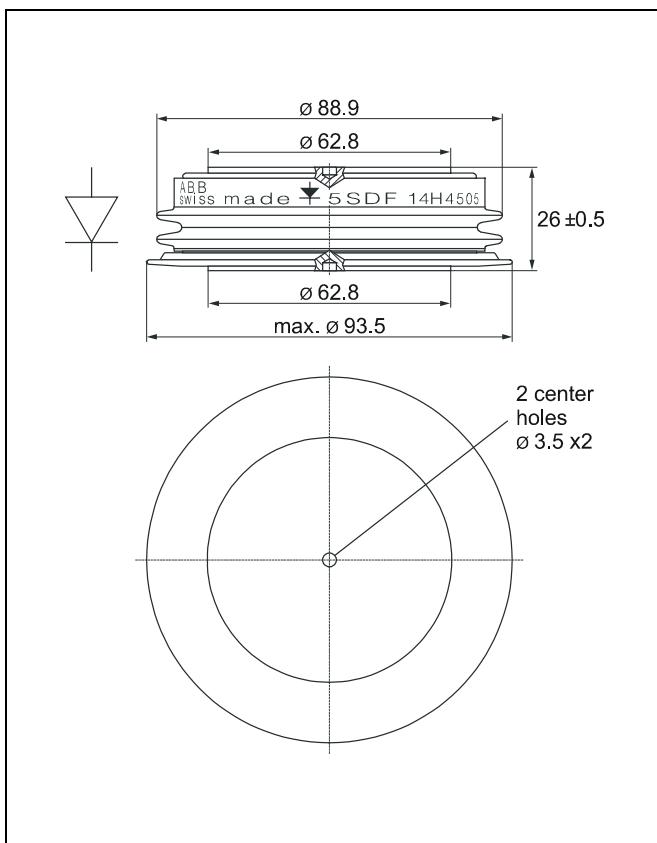


Fig. 11 Turn-off energy vs. turn-off di/dt for $I_F = 3000$ A (max. values).

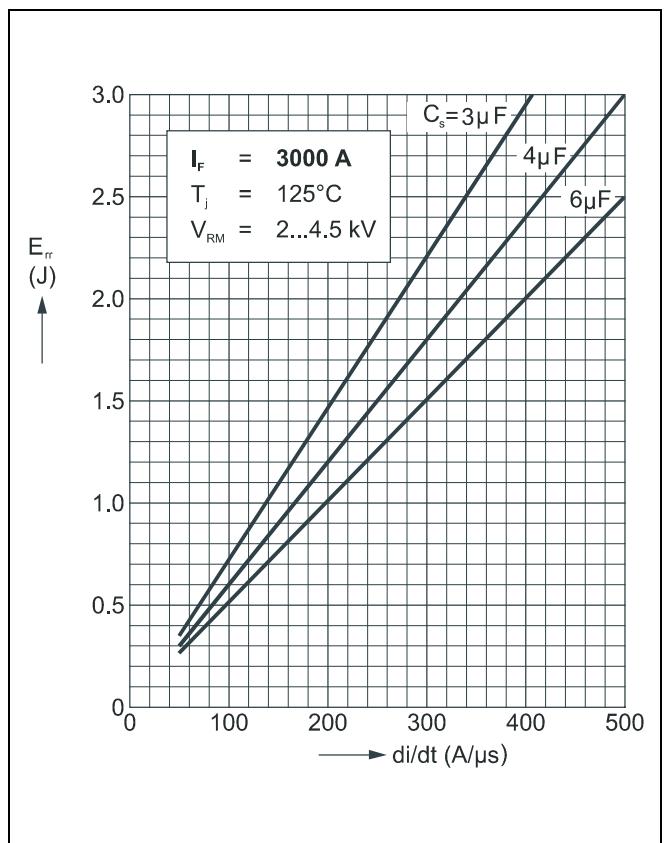


Fig. 12 Transient thermal impedance (junction-to-case) vs. time in analytical and graphical form (max. values).

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ABB

ABB Semiconductors AG
Fabrikstrasse 3
CH-5600 Lenzburg, Switzerland

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Telephone +41 (0)62 888 6419
Fax +41 (0)62 888 6306
Email abbsem@ch.abb.com
Internet www.abbsem.com